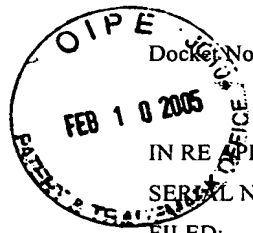


1FW 1775



Docket No. 215240US90PCT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Yasuji HIRAMATSU, et al.

SERIAL NO: 09/926,362

GAU: 1775

FILED: January 16, 2002

EXAMINER: Blackwell-Rudasill, G.A.

FOR: ALUMINUM NITRIDE SINTERED BODY, CERAMIC SUBSTRATE, CERAMIC HEATER AND ELECTROSTATIC CHUCK

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449 and Supplementary European Search Report dated December 8, 2004. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☐ Attached is a list of applicant's pending application(s), published application(s) or issued patent(s) which may be related to the present application. In accordance with the waiver of 37 CFR 1.98 dated September 21, 2004, copies of the cited pending applications are not provided. Cited published and/or issued patents, if any, are listed on the attached PTO form 1449.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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Form PTO 1449
(Modified)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

ATTY DOCKET NO.

215240US90PCT

SERIAL NO.

09/926,362

APPLICANT

Yasuji HIRAMATSU, et al.

FILING DATE

January 16, 2002

GROUP

1775

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA	4,803,183	02/07/1989	Schwetz et al.		
	AB	5,204,080	04/20/1993	Kasori et al.		
	AC					
	AD					
	AE					
	AF					
	AG					
	AH					
	AI					
	AJ					
	AK					
	AL					
	AM					
	AN					

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION	
				YES	NO
	AO				
	AP				
	AQ				
	AR				
	AS				
	AT				
	AU				
	AV				

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

AW	Y. Liu et al., "Microstructure of low-temperature sintered A1N," Materials Letters, Vol. 35, No. 3-4, May 1998, pages 232-235
AX	G. Subhash et al., "Mechanical behaviour of a hot pressed aluminum nitride under uniaxial compression," Journal of Materials Science, Vol. 33, No. 7, 1 April 1998, XP002306549 (Abstract only)
AY	S. R. Witek et al., "Effects of CaO on the strength and toughness of A1N", Journal of the American Ceramic Society, Vol. 72, No. 3, March 1989, XP002306550 (Abstract only)
AZ	<input type="checkbox"/> Additional References sheet(s) attached

Examiner

Date Considered

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.